

SC560N75ZG

Silicon Carbide MOSFET 750V, 560mΩ, 7A



重庆平伟半导体股份有限公司

Features

- 0 V turn-off gate voltage can be applied
- High Blocking Voltage with Low RDS(on)
- High Speed Switching with Low Capacitances
- Easy to Parallel and Simple to Drive
- Qualified according to JEDEC criteria

Applications

- Lighting
- Telecom and UPS
- PWM stages for e.g. PC Silverbox, Adapter, LCD & PDP TV



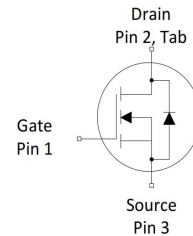
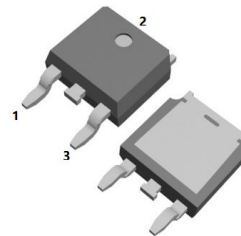
100% DVDS Tested

**100%
Avalanche Tested**

Product Summary

V_{DS}	750V
$R_{DS(on)}$ typ.	560mΩ
I_D	7A

TO-252-2L



Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
SC560N75ZG	SC560N75ZG	TO-252-2L	Tape&Reel	13 inches	16mm	2500

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	750	V
Continuous drain current $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$ (Silicon limit)	I_D	7 5	A
Pulsed drain current ($T_C = 25^\circ\text{C}$)	$I_{D \text{ pulse}}$	21	A
Avalanche energy, single pulse ($L=5\text{mH}$)	E_{AS}	3	mJ
Gate-Source voltage,max.transient voltage	V_{GSmax}	-10/+22	V
Recommended operating values	V_{GSop}	0/+18	V
Power dissipation $T_C = 25^\circ\text{C}$	P_{tot}	27	W
Operating junction and storage temperature	T_j, T_{stg}	-55...+175	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Thermal resistance, junction – case.	R_{thJC}	-	3.7	5.5	°C/W	-
Thermal resistance, junction - ambient(min. footprint)	R_{thJA}	-	-	50	°C/W	1 inch ² , 2oz single copper FR-4 PCB.

Electrical Characteristic (at T_j = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV_{DSS}	750	-	-	V	$V_{GS}=0V, I_D=500\mu A$
Gate threshold voltage	$V_{GS(th)}$	2.7	3.5	4.5	V	$V_{DS}=V_{GS}, I_D=1.3mA$
Zero gate voltage drain current	I_{DSS}	-	1	10	μA	$V_{DS}=750V, V_{GS}=0V$ $T_j=25^\circ C$
		-	-	100	μA	$T_j=175^\circ C$
Gate-source leakage current	I_{GSS}	-	-	100	nA	$V_{GS}=22V, V_{DS}=0V$
		-	-	-100	nA	$V_{GS}=-10V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	560	700	mΩ	$V_{GS}=15V, I_D=3.6A$
Drain-source on-state resistance	$R_{DS(on)}$	-	400	500	mΩ	$V_{GS}=18V, I_D=3.6A$
Transconductance	g_{fs}	-	1.0	-	S	$V_{DS}=20V, I_D=3.6A$

Dynamic Characteristic

Input Capacitance	C_{iss}	-	179	-	pF	$V_{GS}=0V, V_{DS}=400V,$ $f=1MHz$
Output Capacitance	C_{oss}	-	19	-		
Reverse Transfer Capacitance	C_{rss}	-	1	-		
Gate Total Charge	Q_G	-	7.6	-	nC	$V_{DS}=500V, I_D=3.6A$ $, V_{GS}=0V/15V$
Gate-Source charge	Q_{gs}	-	1.7	-		
Gate-Drain charge	Q_{gd}	-	4.2	-		
Turn-on delay time	$t_{d(on)}$	-	10	-	ns	$V_{GS}=0/18V, V_{DD}=400V,$ $R_G=5\Omega, I_D=3.6A$
Rise time	t_r	-	12	-		
Turn-off delay time	$t_{d(off)}$	-	20	-		
Fall time	t_f	-	8	-		
Gate resistance	R_G	-	5.1	-	Ω	$V_{GS}=0V, f=1MHz$

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	4.1	-	V	$V_{GS}=0V, I_{SD}=2.1A$ $T_j=25^{\circ}C$
		-	3.5	-		$T_j=175^{\circ}C$
Body Diode Continuous Forward Current	I_S	-	-	7	A	$T_C = 25^{\circ}C$
		-	-	5	A	$T_C = 100^{\circ}C$
Body Diode Reverse Recovery Time	t_{rr}	-	24	-	ns	$V_{GS}=-5V, I_{SD}=5A,$ $V_R=400V$ $di/dt=1000A/us$
Body Diode Reverse Recovery Charge	Q_{rr}	-	87	-	nC	
Peak Reverse Recovery Current	I_{RRM}	-	3	-	A	

Typical Performance Characteristics

Fig 1: Output Characteristics $T_j=25^\circ\text{C}$

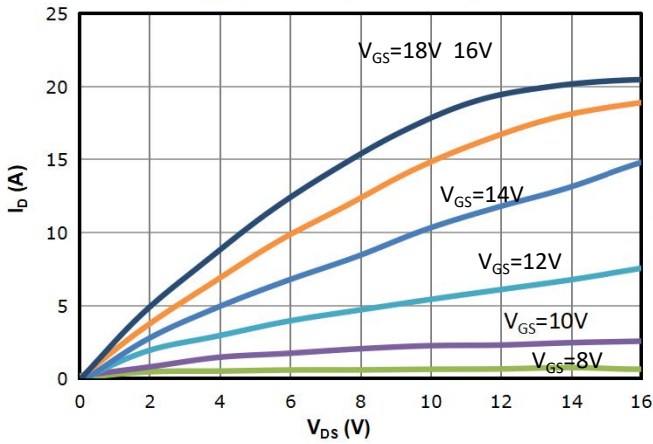


Fig 2: Output Characteristics $T_j=175^\circ\text{C}$

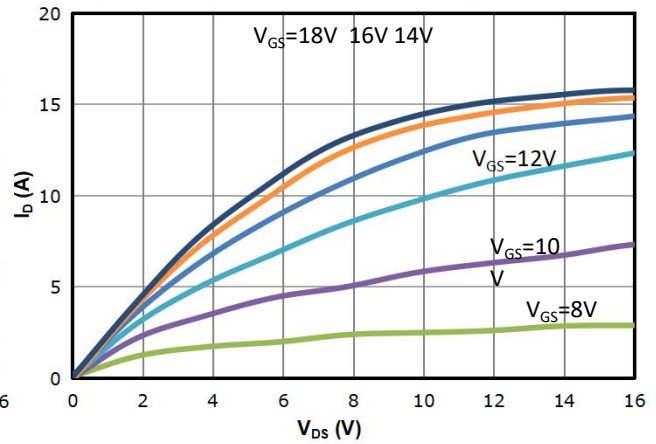


Fig 3: Transfer Characteristics

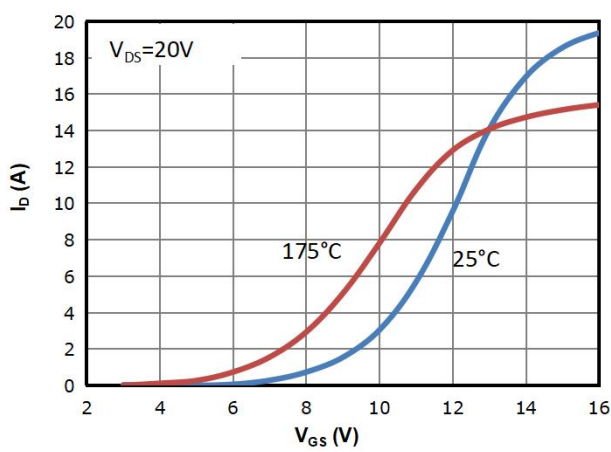


Fig 4: $R_{DS(on)}$ vs Drain Current and Gate Voltage

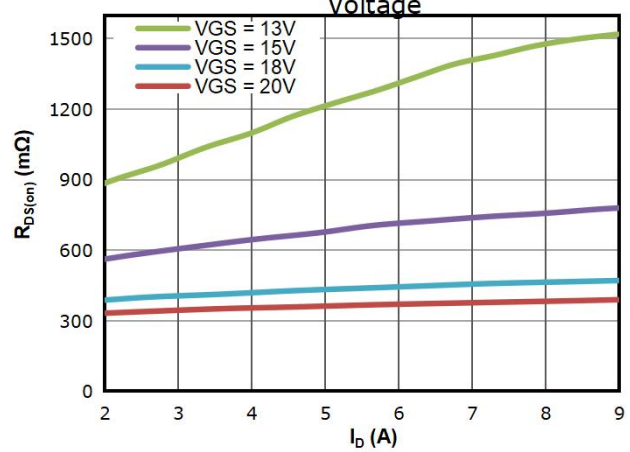


Fig 5: $R_{DS(on)}$ vs. Temperature

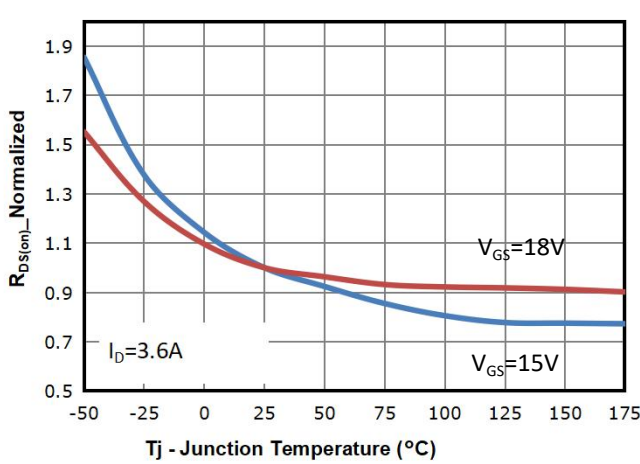


Fig 6: $V_{GS(th)}$ vs. Temperature

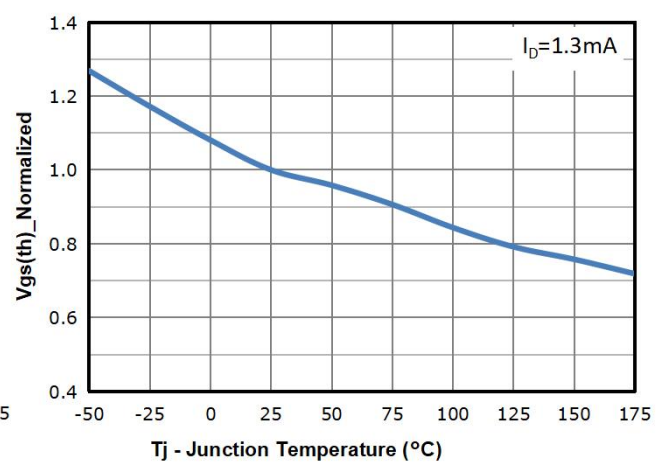


Fig 7: BVdss vs. Temperature

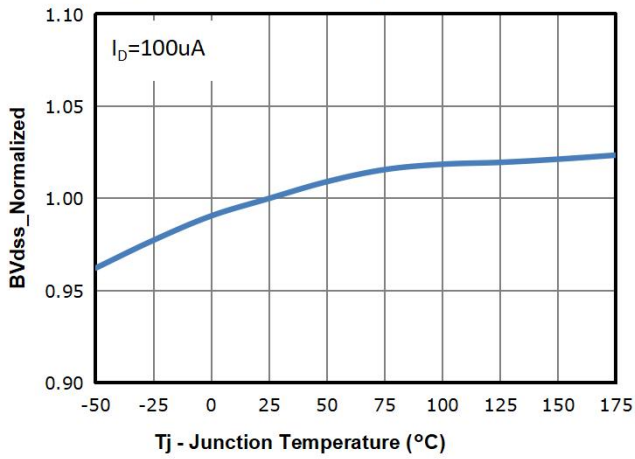


Fig 8: Capacitance Characteristics

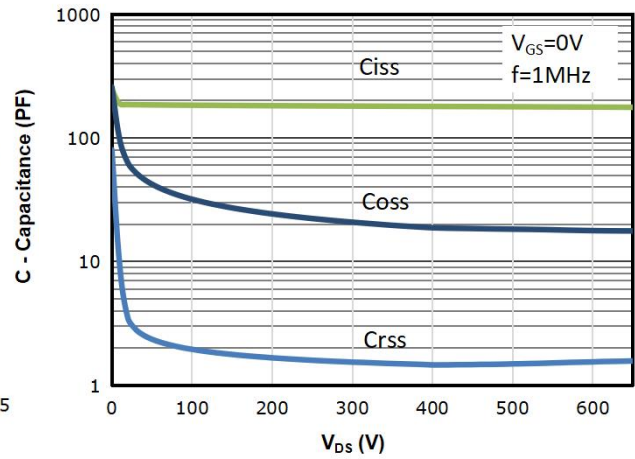


Fig 9: Gate Charge Characteristics

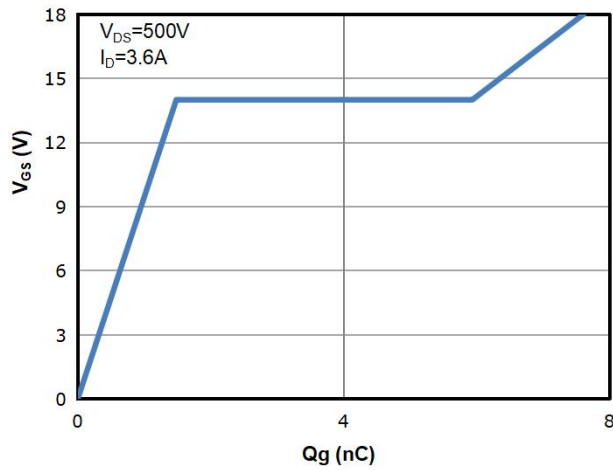


Fig 10: Body-diode Forward Characteristics

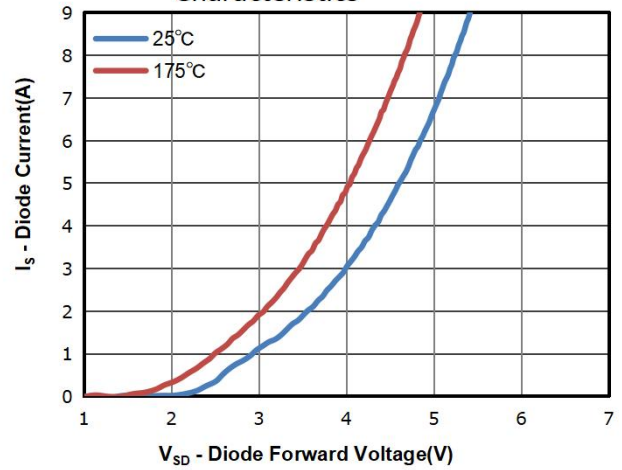


Fig 11: Power Dissipation

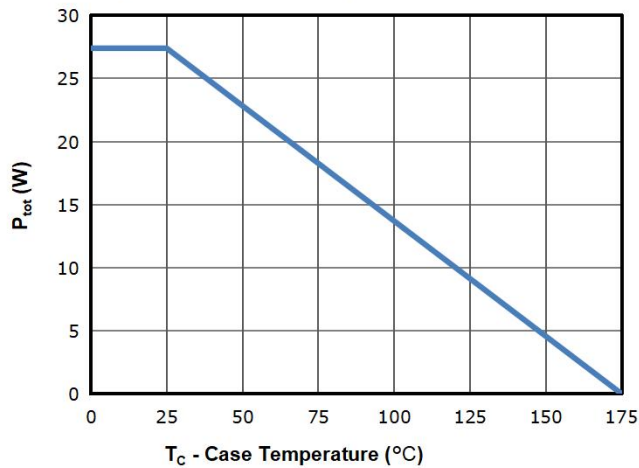


Fig 12: Drain Current Derating

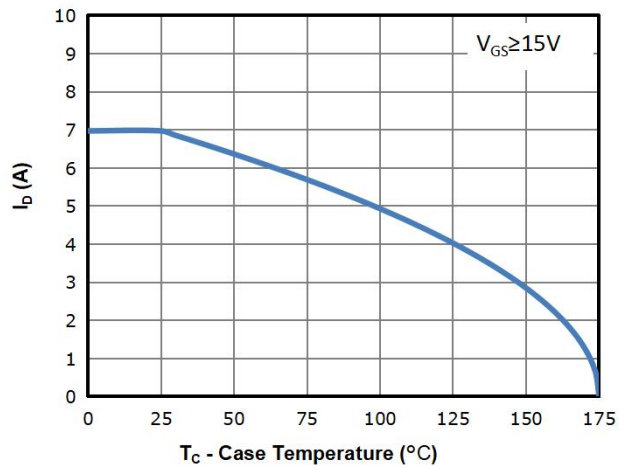




Fig 13: Safe Operating Area

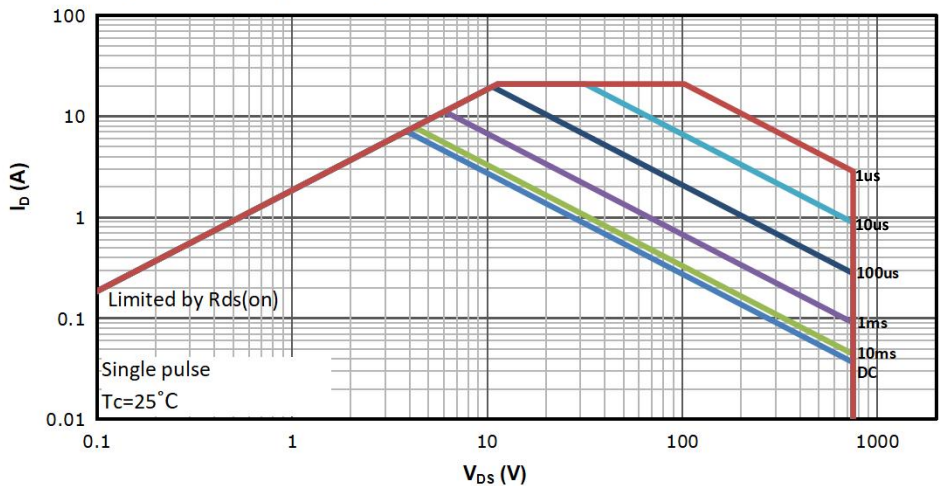
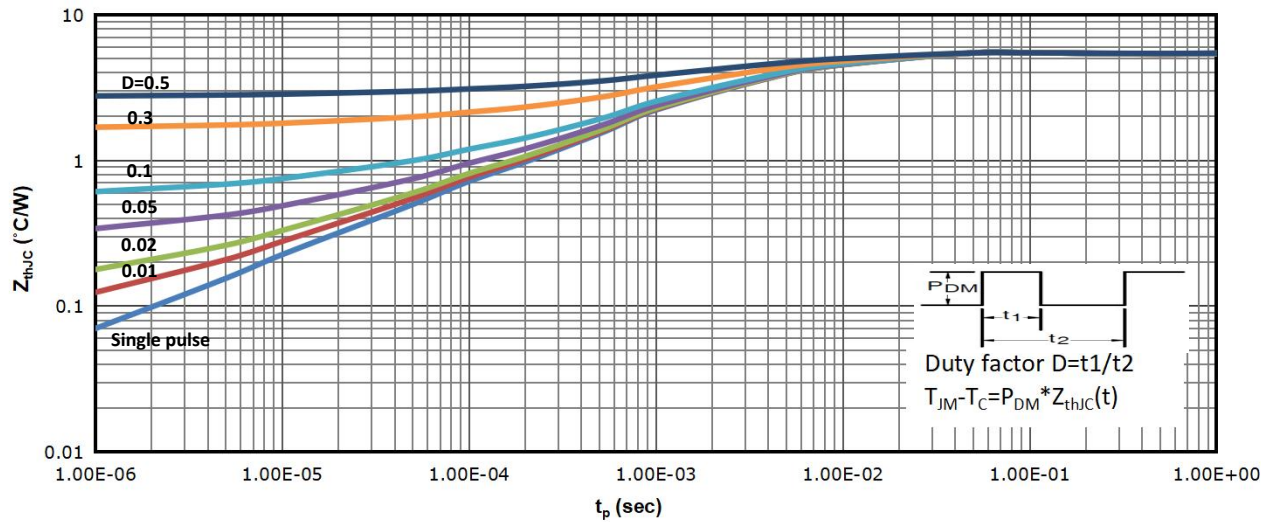
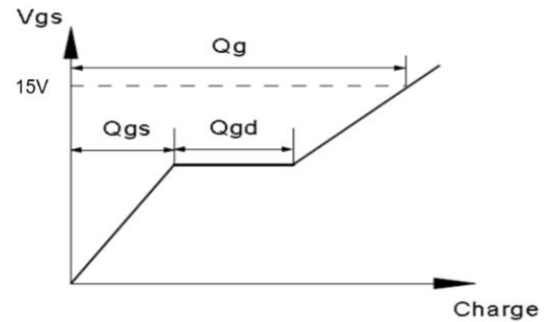
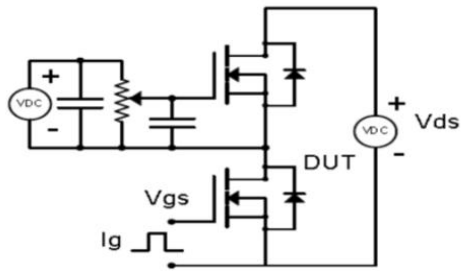


Fig 14: Max. Transient Thermal Impedance

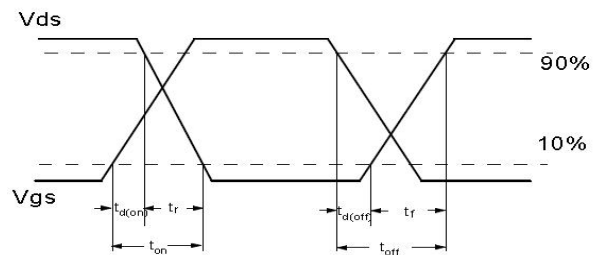
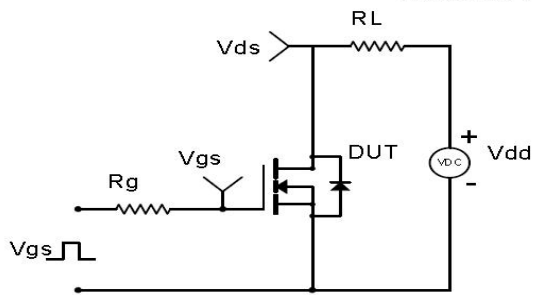


Test Circuit & Waveform

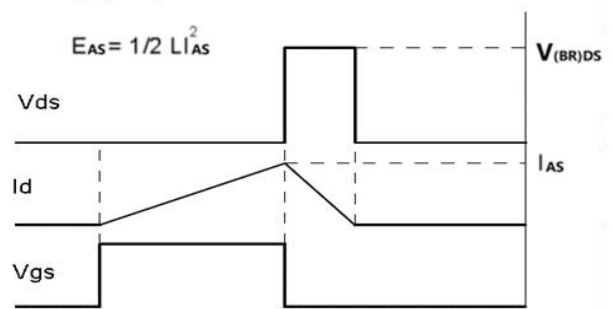
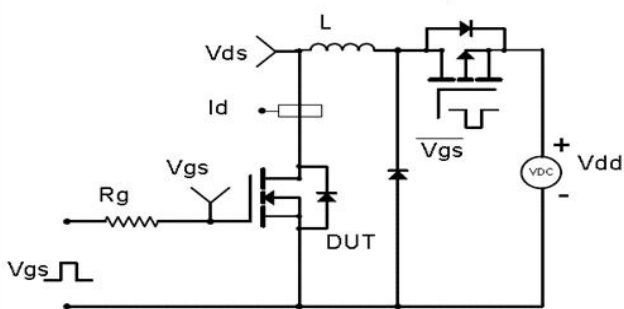
Gate Charge Test Circuit & Waveform



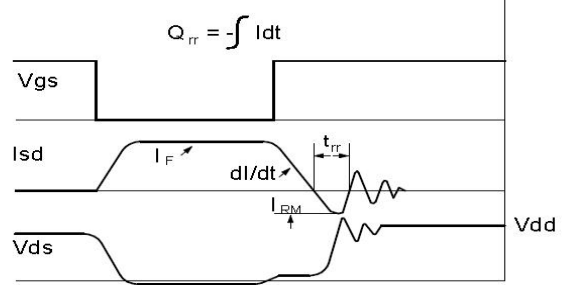
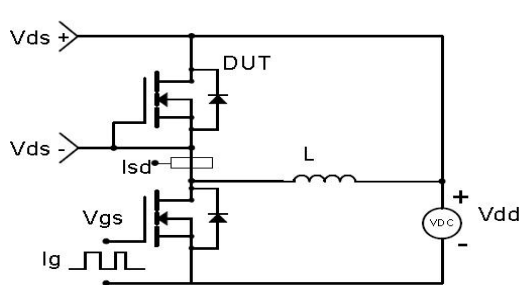
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



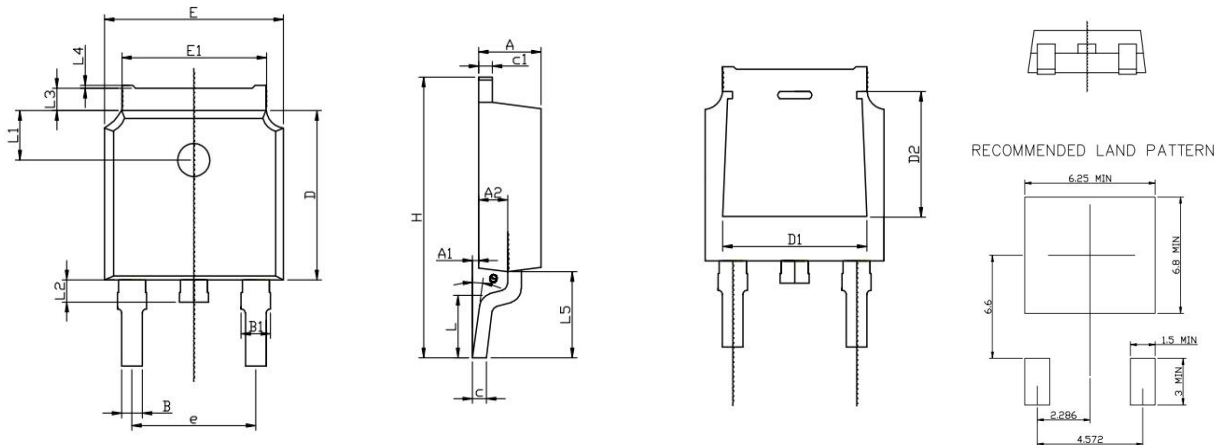
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Package Outline: TO-252-2L



UNIT: mm

SYMBOL	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.15	2.45	0.085	0.096
A1	0.05	0.20	0.002	0.008
A2	0.91	1.22	0.036	0.048
B	0.66	0.86	0.026	0.034
B1	0.93	1.23	0.037	0.048
C	0.40	0.60	0.016	0.024
C1	0.40	0.60	0.016	0.024
D	5.95	6.25	0.234	0.246
D1	4.80		0.189	
D2	3.80		0.150	
E	6.45	6.75	0.254	0.266
E1	5.12	5.52	0.202	0.217
L	1.65		0.065	
L1	1.58	1.98	0.062	0.078
L2	0.60	1.00	0.024	0.039
L3	0.70	1.00	0.028	0.039
L4	0.00	0.20	0.000	0.008
L5	2.80	3.40	0.110	0.134
H	9.80	10.40	0.386	0.409
θ	0.00	8.00	0.000	0.315
e	4.57		0.180	

Disclaimer

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